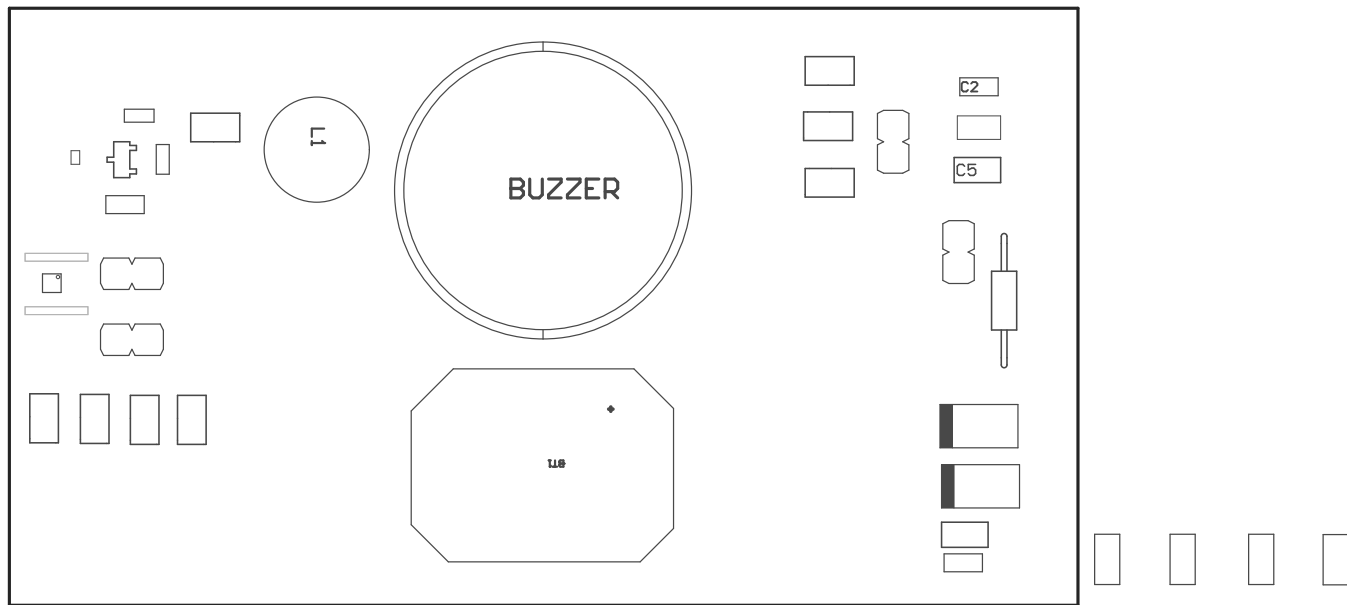


- Z21 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.
- Z22 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
- Z23 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- Z24 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

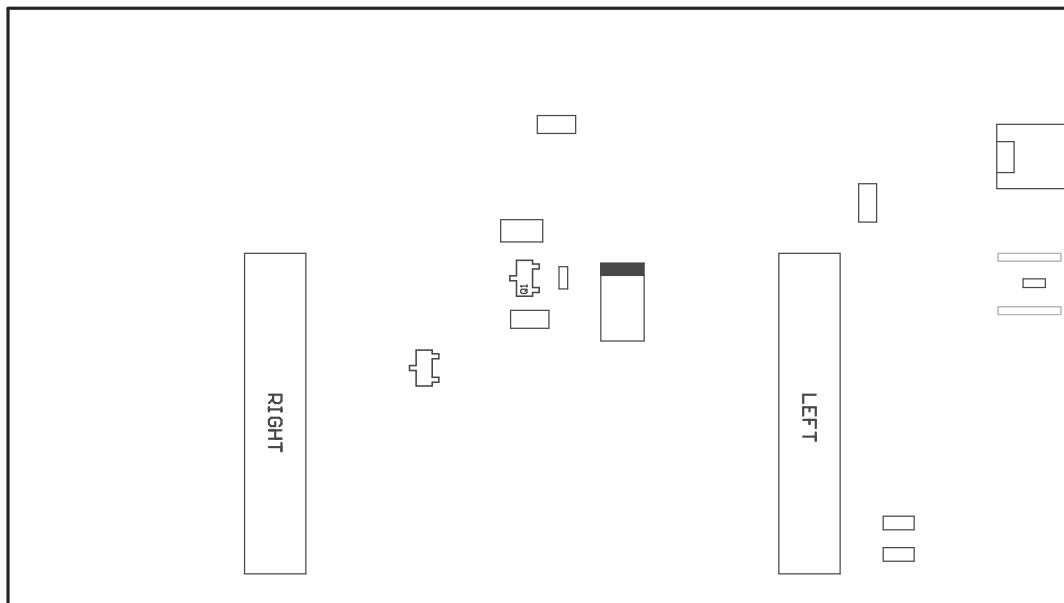


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY URGENT:

001

PCB VIEWED FROM TOP SIDE	BOARD # TIDA-01819	REV# A	SUN REV# Not In VersionControl
	TID # TIDA-01819		
PLOT NAME = Top Assembly Drawing	GENERATED : 8/4/2017	11:01:01 AM	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY UPGRADE:

001

PCB VIEWED FROM BOTTOM SIDE	BOARD # TIDA-C1818	REV A	SUN REV Not In VersionControl
	TID # TIDA-C1818		
PLOT NAME = Bottom Assembly Drawing	GENERATED 8/4/2017	11:01:09 AM	TEXAS INSTRUMENTS

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